

ABSTRACT

A curable aqueous resin emulsion composition containing: 100 parts by mass of a (meth)acrylate epoxy resin (a); from 1 to 200 parts by mass of a polymerizable unsaturated monomer (b); from 0.1 to 10 parts by mass of a curing accelerator (c); from 1 to 50 parts by mass of a reactive surfactant (d); from 10 to 2,000 parts by mass of water (e); a radical polymerization initiator (f); and at least one of a component (g) and a component (h) below: (g) at least one selected from inorganic particles and organic particles, and (h) at least one compound selected from an alkoxysilane compound, a metal alkoxy compound, a metal chelate compound, an epoxy compound, an isocyanate compound, and a triazine compound.